PDP_MB_R1.0_U14_DUTPWR_0x28_R1.0

General Description

Renesas SLG7RN46354 is a low power and small form device. The SoC is housed in a 2mm x 3mm STQFN package which is optimal for using with small devices.

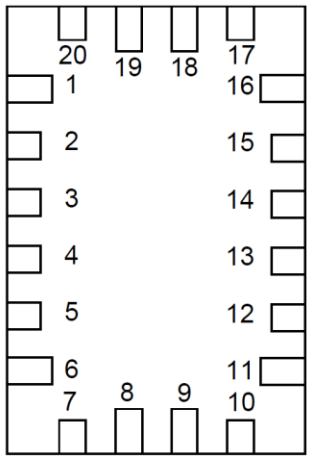
Features

- Low Power Consumption
- Pb - Free / RoHS Compliant
- Halogen - Free
- STQFN - 20 Package

Output Summary

7 Outputs - Push Pull 2X

Pin Configuration

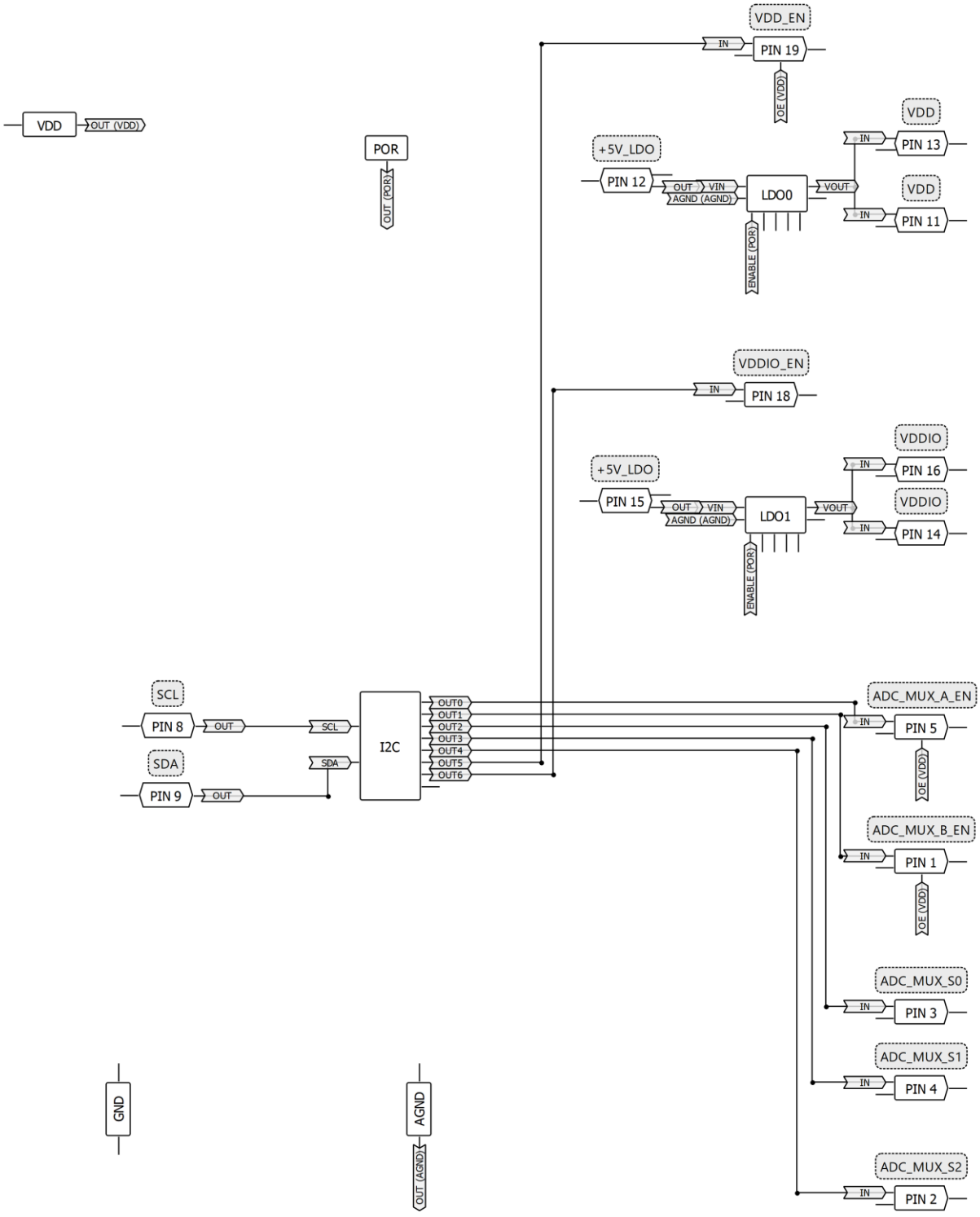


STQFN-20
(Top view)

Pin name

Pin #	Pin name	Pin #	Pin name
1	ADC_MUX_B_EN	11	VDD
2	ADC_MUX_S2	12	+5V_LDO
3	ADC_MUX_S0	13	VDD
4	ADC_MUX_S1	14	VDDIO
5	ADC_MUX_A_EN	15	+5V_LDO
6	NC	16	VDDIO
7	VDD	17	AGND
8	SCL	18	VDDIO_EN
9	SDA	19	VDD_EN
10	NC	20	GND

Block Diagram



Pin Configuration

Pin #	Pin Name	Type	Pin Description	Internal Resistor
1	ADC_MUX_B_EN	Digital Output	Push Pull 2X	floating
2	ADC_MUX_S2	Digital Output	Push Pull 2X	floating
3	ADC_MUX_S0	Digital Output	Push Pull 2X	floating
4	ADC_MUX_S1	Digital Output	Push Pull 2X	floating
5	ADC_MUX_A_EN	Digital Output	Push Pull 2X	floating
6	NC	--	Keep Floating or Connect to GND	--
7	VDD	PWR	Supply Voltage	--
8	SCL	Digital Input	Low Voltage Digital Input	floating
9	SDA	Digital Input	Low Voltage Digital Input	floating
10	NC	--	Keep Floating or Connect to GND	--
11	VDD	Analog Output	LDO0 VOUT Analog Output	floating
12	+5V_LDO	Analog Input	LDO0 VIN Analog Input	floating
13	VDD	Analog Output	LDO0 VOUT Analog Output	floating
14	VDDIO	Analog Output	LDO1 VOUT Analog Output	floating
15	+5V_LDO	Analog Input	LDO1 VIN Analog Input	floating
16	VDDIO	Analog Output	LDO1 VOUT Analog Output	floating
17	AGND	AGND	Ground	--
18	VDDIO_EN	Digital Output	Push Pull 2X	floating
19	VDD_EN	Digital Output	Push Pull 2X	floating
20	GND	GND	Ground	--

Ordering Information

Part Number	Package Type
SLG7RN46354V	20-pin STQFN
SLG7RN46354V	20-pin STQFN - Tape and Reel (3k units)

Absolute Maximum Conditions

Parameter		Min.	Max.	Unit
Supply Voltage on VDD relative to GND		-0.3	7	V
DC Input Voltage		GND - 0.5V	VDD + 0.5V	V
Maximum Average or DC Current (Through pin)	Push-Pull 2x	--	43	mA
Current at Input Pin		-1.0	1.0	mA
Input leakage (Absolute Value)		--	1000	nA
Storage Temperature Range		-65	150	°C
Junction Temperature		--	150	°C
ESD Protection (Human Body Model)		2000	--	V
ESD Protection (Charged Device Model)		1300	--	V
Moisture Sensitivity Level		1		

Electrical Characteristics

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
V_{DD}	Supply Voltage		2.3	3.3	5.5	V
T_A	Operating Temperature		-40	25	85	°C
C_{VDD}	Capacitor Value at VDD		--	0.1	--	µF
C_{IN}	Input Capacitance		--	4	--	pF
I_Q	Quiescent Current	Static inputs and floating outputs	--	23	--	µA
V_O	Maximal Voltage Applied to any PIN in High-Impedance State		--	--	VDD+0.3	V
I_{VDD}	Maximum Average or DC Current Through VDD Pin (Per chip side, see Note 2)	T_J = 85°C	--	--	73	mA
		T_J = 110°C	--	--	35	mA
I_{GND}	Maximum Average or DC Current Through GND Pin (Per chip side, see Note 2)	T_J = 85°C	--	--	152	mA
		T_J = 110°C	--	--	72	mA
V_{IH}	HIGH-Level Input Voltage	Low-Level Logic Input	1.25	--	VDD+0.3	V
V_{IL}	LOW-Level Input Voltage	Low-Level Logic Input	GND-0.3	--	0.5	V
V_{OH}	HIGH-Level Output Voltage	Push-Pull 2X, I_{OH}=100µA at VDD=2.5V	2.29	2.50	--	V
		Push-Pull 2X, I_{OH}=3mA at VDD=3.3V	2.87	3.21	--	V
		Push-Pull 2X, I_{OH}=5mA at VDD=5.0V	4.32	4.89	--	V
V_{OL}	LOW-Level Output Voltage	Push-Pull 2X, I_{OL}=100µA, at VDD=2.5V	--	0.03	0.06	V
		Push-Pull 2X, I_{OL}=3mA, at VDD=3.3V	--	0.06	0.11	V
		Push-Pull 2X, I_{OL}=5mA, at VDD=5.0V	--	0.08	0.14	V
I_{OH}	HIGH-Level Output Current (Note 1)	Push-Pull 2X, V_{OH}=VDD-0.2V at VDD=2.5V	2.22	3.41	--	mA
		Push-Pull 2X, V_{OH}=2.4V at VDD=3.3V	11.54	24.16	--	mA

		Push-Pull 2X, V_{OH}=2.4V at VDD=5.0V	41.46	68.08	--	mA
I_{OL}	LOW-Level Output Current (Note 1)	Push-Pull 2X, V_{OL}=0.15V, at VDD=2.5V	1.83	3.38	--	mA
		Push-Pull 2X, V_{OL}=0.4V, at VDD=3.3V	9.75	16.49	--	mA
		Push-Pull 2X, V_{OL}=0.4V, at VDD=5.0V	13.83	23.16	--	mA
LDO0	LDO0 output voltage	Vout0 voltage	--	0.90	--	V
		Vout1 voltage	--	0.90	--	V
LDO1	LDO1 output voltage	Vout0 voltage	--	0.90	--	V
		Vout1 voltage	--	0.90	--	V
T_{SU}	Startup Time	From VDD rising past PON_{THR}	--	1.3	--	ms
PON_{THR}	Power On Threshold	V_{DD} Level Required to Start Up the Chip	1.34	1.55	1.74	V
$POFF_{THR}$	Power Off Threshold	V_{DD} Level Required to Switch Off the Chip	1.05	1.25	1.45	V

Note:
1. DC or average current through any pin should not exceed value given in Absolute Maximum Conditions.
2. The GreenPAK's power rails are divided in two sides. PINs 1, 2, 3, 4, 5 and 6 are connected to one side, PINs 8, 9, 10, 18 and 19 to another.
3. Guaranteed by Design.

I²C Specifications

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
F_{SCL}	Clock Frequency, SCL	V_{DD} = (2.3...5.5) V	--	--	400	kHz
t_{LOW}	Clock Pulse Width Low	V_{DD} = (2.3...5.5) V	1300	--	--	ns
t_{HIGH}	Clock Pulse Width High	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_I	Input Filter Spike Suppression (SCL, SDA)	V_{DD} = 2.5V ± 8%	--	--	168	ns
		V_{DD} = 3.3V ± 10%	--	--	157	ns
		V_{DD} = 5.0V ± 10%	--	--	156	ns
t_{AA}	Clock Low to Data Out Valid	V_{DD} = (2.3...5.5) V	--	--	900	ns
t_{BUF}	Bus Free Time between Stop and Start	V_{DD} = (2.3...5.5) V	1300	--	--	ns
t_{HD_STA}	Start Hold Time	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_{SU_STA}	Start Set-up Time	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_{HD_DAT}	Data Hold Time	V_{DD} = (2.3...5.5) V	0	--	--	ns
t_{SU_DAT}	Data Set-up Time	V_{DD} = (2.3...5.5) V	100	--	--	ns
t_R	Inputs Rise Time	V_{DD} = (2.3...5.5) V	--	--	300	ns
t_F	Inputs Fall Time	V_{DD} = (2.3...5.5) V	--	--	300	ns
t_{SU_STO}	Stop Set-up Time	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_{DH}	Data Out Hold Time	V_{DD} = (2.3...5.5) V	50	--	--	ns

LDO Regulator Thermal Limitations

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
IC_{TL}	Thermal Limitation	85 °C ambient, Total IC package	--	--	0.6	W
		70 °C ambient, Total IC package	--	--	0.8	W

		Max Watt per LDO[1]	--	--	0.5	W
Shutdown	Thermal Shutdown[2]		115	125	135	°C
	Thermal Shutdown Recovery		90	100	110	°C

Note:
1. Please note that Max Watt LDO multiplied by number of LDOs can easily exceed the Max Watt for the total IC package. In this case an external resistor should be used on LDO Vin to lower the voltage drop across the LDO Regulator.
2.Lower Thermal shutdown levels may be achieved by using the temperature sensor and comparator.

LDO HP MODE Electrical Specifications

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
I_{OUT}	Output Current Rating		--	--	300	mA
V_{IN}	Voltage Input		2.3	--	VDD	V
V_{DO}	Voltage Dropout		--	250	300	mV
ΔV_{OUT}	Output Voltage Accuracy (see Note 1)	over PVT of V_{OUT} > 1.5 V	-3	--	+3	%
		over PVT of V_{OUT} ≤ 1.5 V	-60	--	+60	mV
e_N	Noise Voltage (rms)	10 Hz to 100 kHz	--	75	--	µV
PSRR	Power Supply Rejection Ratio (see Note 2)	100 Hz to 100 kHz	TBD	50	--	dB
CTRR	Crosstalk Rejection Ratio	LDO0 to LDO1 regulation perturbation, and LDO2 to LDO3 perturbation at 0 to 150 mA at 1 kHz at 1.8 V V_{OUT}	TBD	50	--	dB
ΔV_{LINE}	Line Regulation	V_{OUT} + 0.5 V < V_{IN} ≤ 5.5 V	-1%	--	+1%	%/V
ΔV_{LOAD}	Load Regulation	1 mA < I_{OUT} < 150 mA	--	--	0.3	mV/ mA
ΔV_{TC}	V_{OUT} Temp Coefficient		--	100	--	ppm/ C
C_{IN}	External Input Capacitor (see Note 2)		2	--	--	µF
C_{OUT}	External Output Capacitor		4	--	--	µF
t_{SS_0}	Soft Start Option 0 Time	V_{OUT} 5% to 95%	-20%	10	+20%	V/ms
t_{SS_1}	Soft Start Option 1 Time	V_{OUT} 5% to 95%	-20%	20	+20%	V/ms
t_{SS_2}	Soft Start Option 2 Time	V_{OUT} 5% to 95%	-30%	1.25	+30%	V/ms
t_{SS_3}	Soft Start Option 3 Time	V_{OUT} 5% to 95%	-30%	2.50	+30%	V/ms
SC	Short Circuit Protection		TBD	TBD	TBD	mA
t_{WAIT}	Wait Time	Time from EN=1 to V_{OUT} start rise	--	500	--	µs
R_D	Output Discharge Pull-down Resistance	EN=0, Dis_EN = 1	--	300	--	Ω

Note:
1. Accuracy specifies all the effects of line regulation (ΔV_{LINE}), load regulation (ΔV_{LOAD}), and temperature coefficient (ΔV_{TC}),
2. X7R-type and X5R-type capacitors are recommended

Chip address

HEX	BIN	DEC
0x28	0101000	40

I2C Description

1. I2C Basic Command Structure

Each command to the I2C Serial Communications block begins with a Control Byte. The bits inside this Control Byte are shown in Figure 1. After the Start bit, the first four bits are a control code, which can be set by the user in reg<1867:1864>. The Block Address is the next three bits (A10, A9, A8), which will define the most significant bits in the addressing of the data to be read (“1”) or written (“0”) by the command. This Control Byte will be followed by an Acknowledge bit (ACK).

With the exception of the Current Address Read command, all commands will have the Control Byte followed by the Word Address. The Word Address, in conjunction with the three address bits in the Control Byte, will define the specific data byte to be read or written in the command. Figure 1 shows this basic command structure.

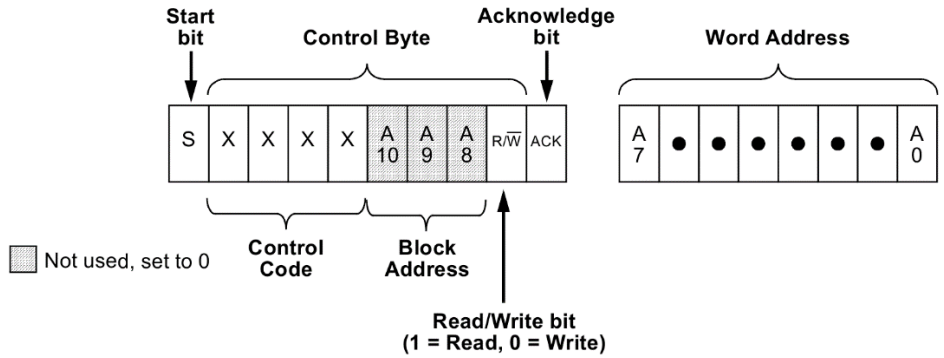


Figure1. I2C Basic Command Structure

2. I2C Serial General Timing

Shown in Figure 2 is the general timing characteristics for the I2C Serial Communications block.

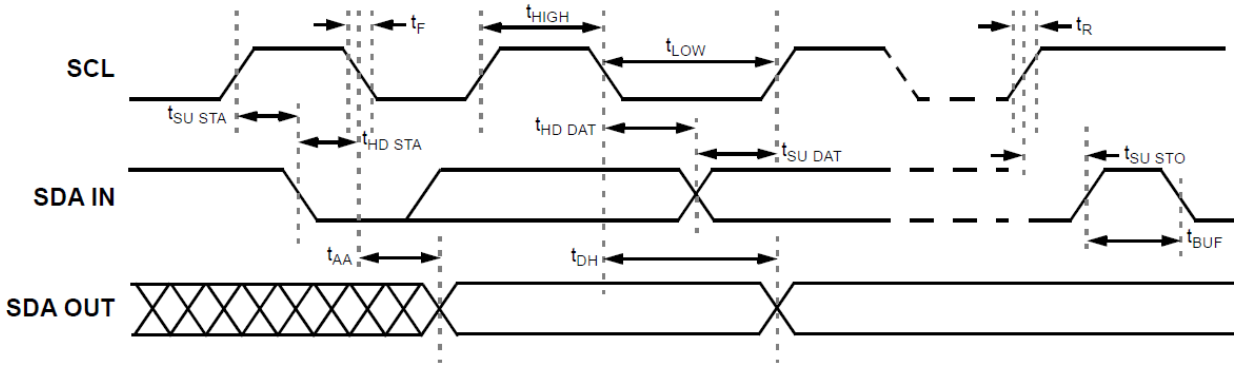


Figure2. I2C Serial General Timing

3. I2C Serial Communications: Read and Write Commands

Following the Start condition from the master, the Control Code [4 bits], the block address [3 bits] and the R/W bit (set to “0”), is placed onto the bus by the Bus Master. After the I2C Serial Communications block has provided an Acknowledge bit (ACK) the next byte transmitted by the master is the Word Address. The Block Address is the next three bits, and is the higher order addressing bits (A10, A9, A8), which when added to the Word Address will together set the internal address pointer in the SLG7RN46354 to the correct data byte to be written. After the SLG7RN46354 sends another Acknowledge bit, the Bus Master will transmit the data byte to be written into the addressed memory location. The SLG7RN46354 again provides an Acknowledge bit and then the Bus Master generates a Stop condition. The internal write cycle for the data will take place at the time that the SLG7RN46354 generates the Acknowledge bit.

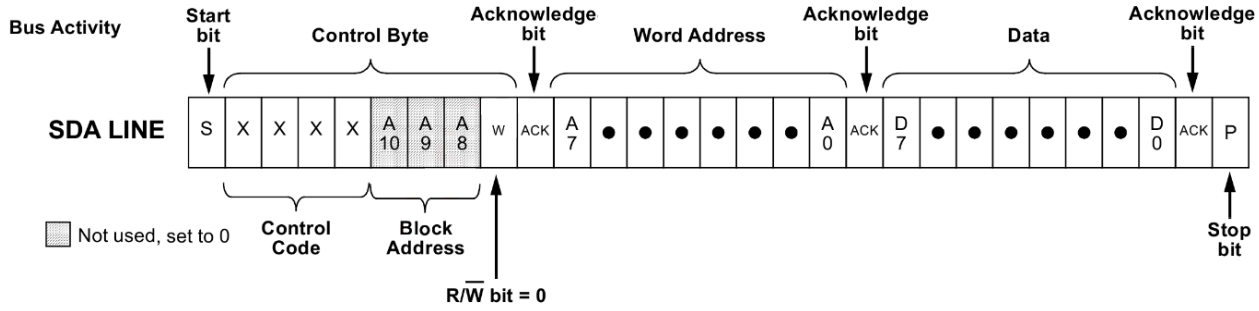


Figure3. I2C Write Command

The Random Read command starts with a Control Byte (with R/$\overline{W}$ bit set to “0”, indicating a write command) and Word Address to set the internal byte address, followed by a Start bit, and then the Control Byte for the read (exactly the same as the Byte Write command). The Start bit in the middle of the command will halt the decoding of a Write command, but will set the internal address counter in preparation for the second half of the command. After the Start bit, the Bus Master issues a second control byte with the R/$\overline{W}$ bit set to “1”, after which the SLG7RN46354 issues an Acknowledge bit, followed by the requested eight data bits.

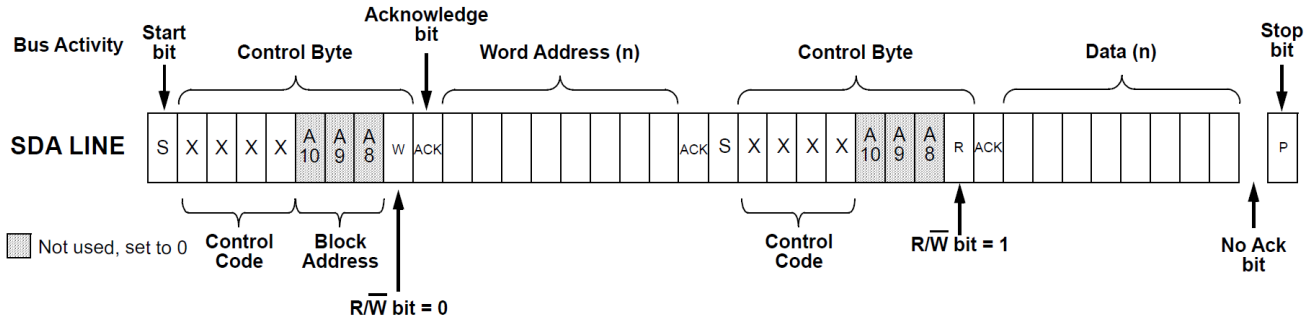


Figure4. I2C Random Read Command

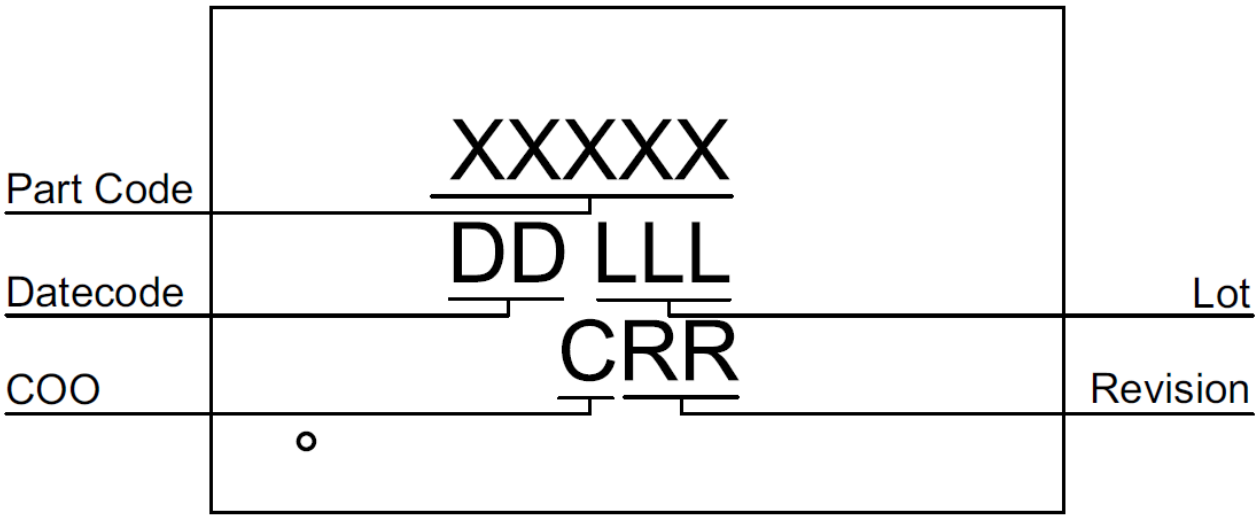
4. I2C register control data

Address Byte	Register Bit	Block	Function
0xF4	reg<1952>	Virtual Input <0>	Control PIN5(ADC_MUX_A_EN) logic, Default is 0.
	reg<1953>	Virtual Input <1>	Control PIN1(ADC_MUX_B_EN) logic, Default is 0.
	reg<1954>	Virtual Input <2>	Control PIN3(ADC_MUX_S0) logic, Default is 0.
	reg<1955>	Virtual Input <3>	Control PIN4(ADC_MUX_S1) logic, Default is 0.
	reg<1956>	Virtual Input <4>	Control PIN2(ADC_MUX_S2) logic, Default is 1.
	reg<1957>	Virtual Input <5>	Control PIN19(VDD_EN) logic, Default is 0.
	reg<1958>	Virtual Input <6>	Control PIN18(VDDIO_EN) logic, Default is 0.

5. I2C Commands:

1. [start] [0x08] [w] [0xF4] [xxxxxxx(OUT0)] [stop] // Control PIN5(ADC_MUX_A_EN) output
2. [start] [0x08] [w] [0xF4] [xxxxxx(OUT1)x] [stop] // Control PIN1(ADC_MUX_B_EN) output
3. [start] [0x08] [w] [0xF4] [xxxxx(OUT2)xx] [stop] // Control PIN3(ADC_MUX_S0) output
4. [start] [0x08] [w] [0xF4] [xxxx(OUT3)xxx] [stop] // Control PIN4(ADC_MUX_S1) output
5. [start] [0x08] [w] [0xF4] [xxx(OUT4)xxxx] [stop] // Control PIN2(ADC_MUX_S2) output
6. [start] [0x08] [w] [0xF4] [xx(OUT5)xxxxx] [stop] // Control PIN19(VDD_EN) output
7. [start] [0x08] [w] [0xF4] [x(OUT6)xxxxxx] [stop] // Control PIN18(VDDIO_EN) output

Package Top Marking



XXXXX – Part ID Field: identifies the specific device configuration
DD – Date Code Field: Coded date of manufacture
LLL – Lot Code: Designates Lot #
C – Assembly Site/COO: Specifies Assembly Site/Country of Origin
RR – Revision Code: Device Revision

Datasheet Revision	Programming Code Number	Lock Status	Checksum	Part Code	Revision	Date
0.11	001	U	0x192706FC	46354	AA	04/13/2023

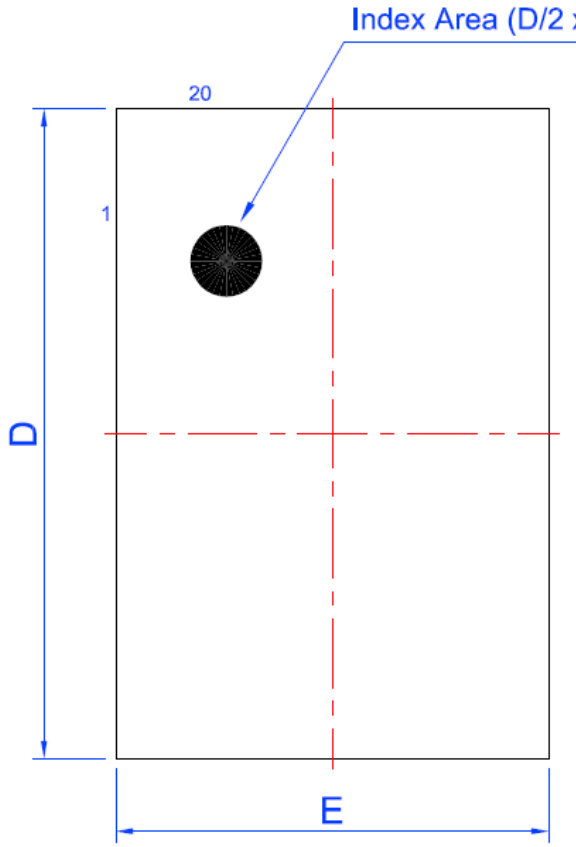
Lock coverage for this part is indicated by √, from one of the following options:

√	Unlocked
	Locked for read, bits <1535:0>
	Locked for write, bits <1535:0>
	Locked for write all bits
	Locked for read and write bits <1535:0>
	Locked for read bits <1535:0> and write of all bits

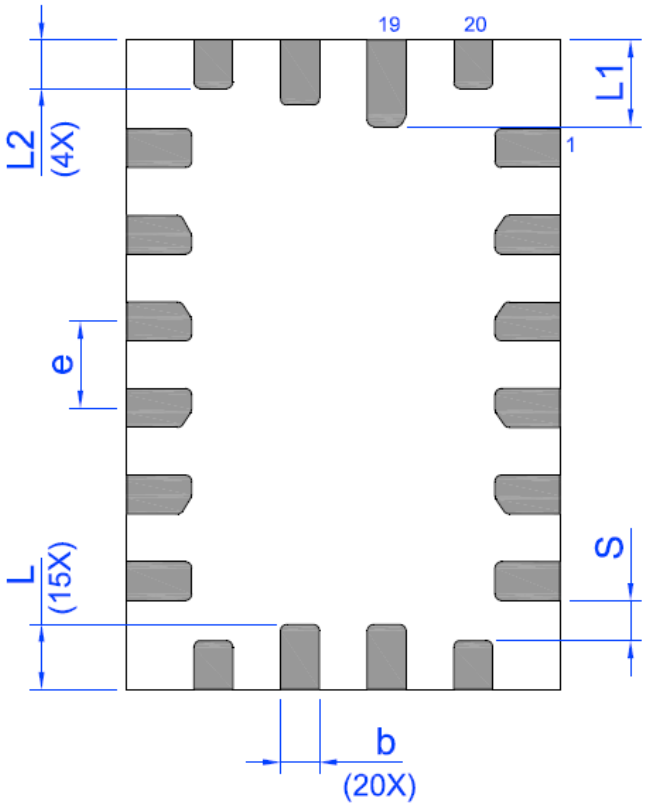
The IC security bit is locked/set for code security for production unless otherwise specified. The Programming Code Number is not changed based on the choice of locked vs. unlocked status.

Package Drawing and Dimensions

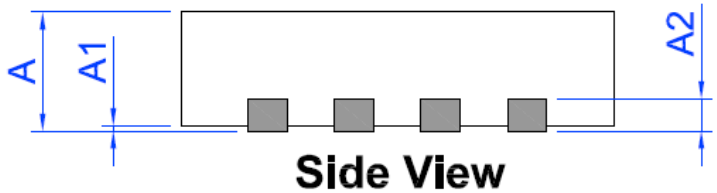
STQFN 20L 2x3mm 0.4P FCD Package
JEDEC MO-220, Variation WECE



Marking View



BTM View



Side View

Unit: mm

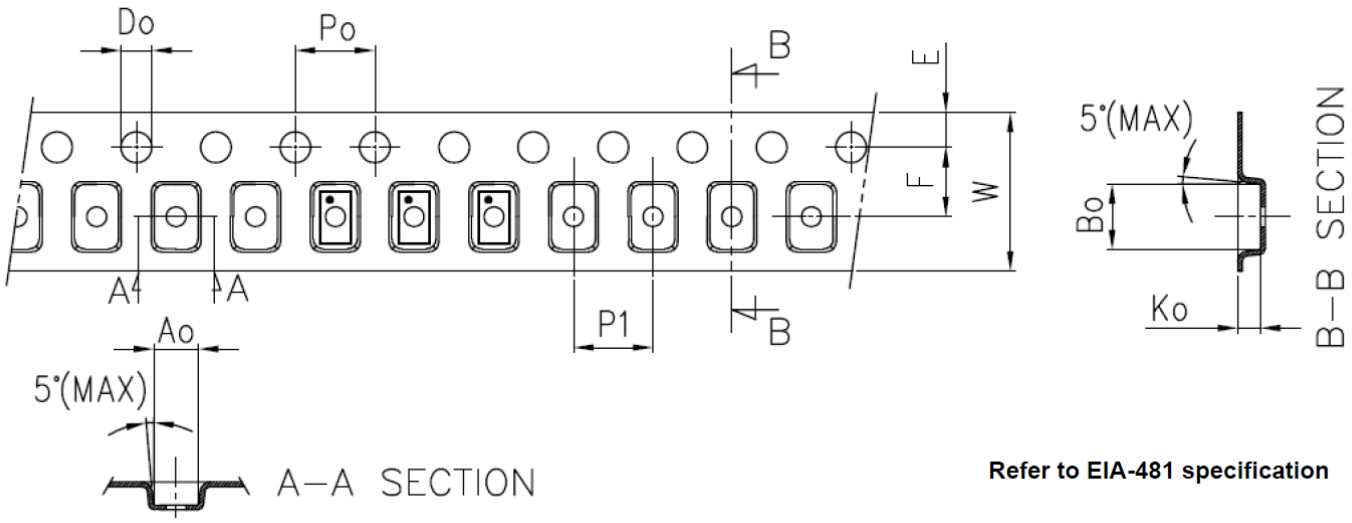
Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.50	0.55	0.60	D	2.95	3.00	3.05
A1	0.005	-	0.050	E	1.95	2.00	2.05
A2	0.10	0.15	0.20	L	0.25	0.30	0.35
b	0.13	0.18	0.23	L1	0.35	0.40	0.45
e	0.40 BSC			L2	0.175	0.225	0.275
S	0.185 TYP						

Tape and Reel Specification

Package Type	# of Pins	Nominal Package Size [mm]	Max Units		Reel & Hub Size [mm]	Leader (min)		Trailer (min)		Tape Width [mm]	Part Pitch [mm]
			per Reel	per Box		Pockets	Length [mm]	Pockets	Length [mm]		
STQFN 20L 2x3mm 0.4P FCD	20	2 x 3 x 0.55	3000	3000	178/60	100	400	100	400	8	4

Carrier Tape Drawing and Dimensions

Package Type	Pocket BTM Length	Pocket BTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge	Index Hole to Pocket Center	Tape Width
	A0	B0	K0	P0	P1	D0	E	F	W
STQFN 20L 2x3mm 0.4P FCD	2.2	3.15	0.76	4	4	1.5	1.75	3.5	8



Refer to EIA-481 specification

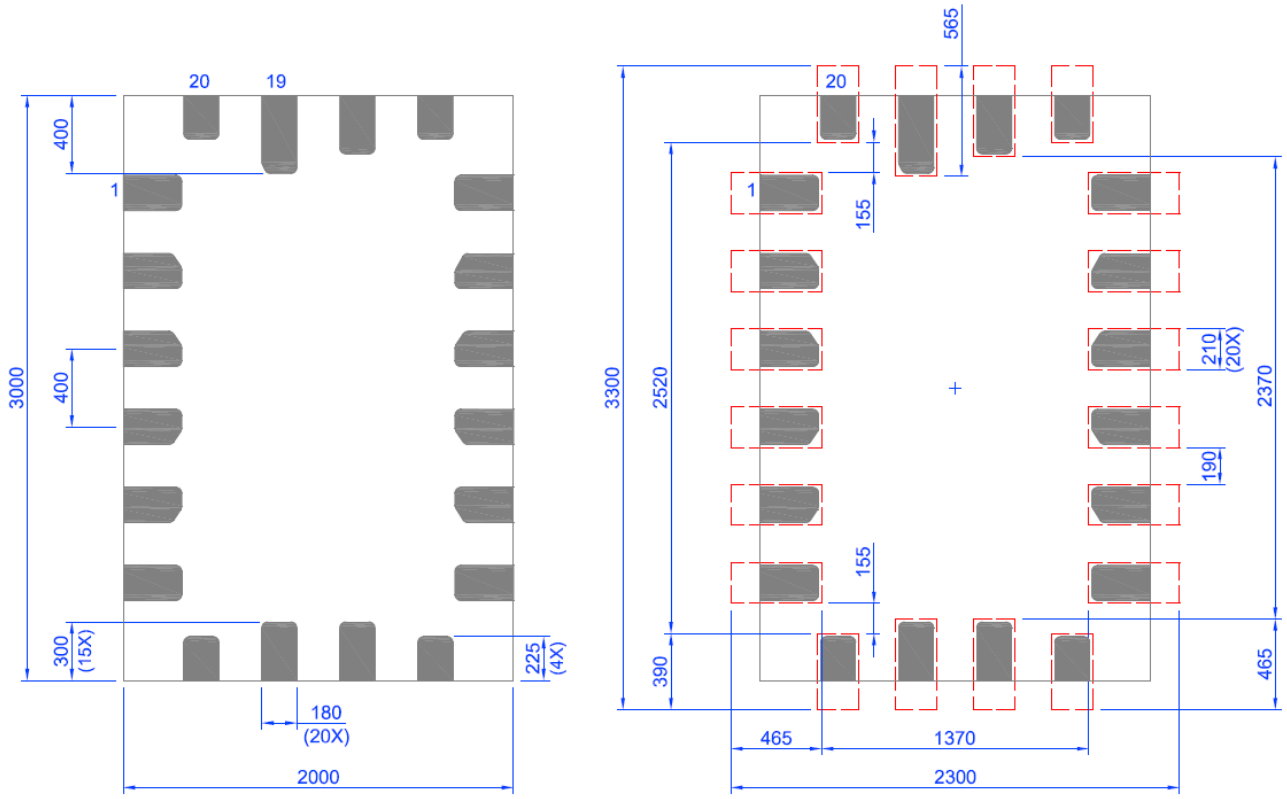
Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 3.30 mm^3 (nominal). More information can be found at www.jedec.org.

Recommended Land Pattern

Exposed Pad
(PKG face down)

Recommended Land Pattern
(PKG face down)



Unit:um

Datasheet Revision History

Date	Version	Change
03/06/2023	0.10	New design for SLG46582 chip
04/13/2023	0.11	Updated Device Revision Table

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